

Features

- Split Gate Trench MOSFET Technology
- Excellent package for heat dissipation
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

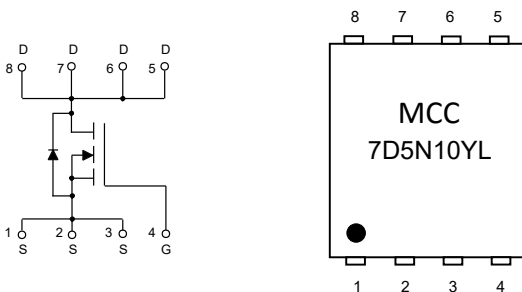
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance:50°C/W Junction to Ambient^(Note2)
- Thermal Resistance:1.4°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	T _C =25°C	75
		T _C =100°C	47
Pulsed Drain Current ^(Note3)	I _{DM}	300	A
Total Power Dissipation ^(Note4)	P _D	89	W
Single Pulse Avalanche Energy ^(Note 5)	E _{AS}	225	mJ

Note:

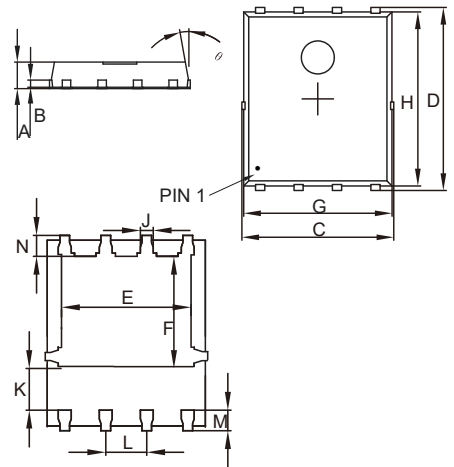
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. T_J=25°C, V_{DD}=50V, V_{GS}=10V, R_G=25Ω, L=2mH.

⚠️ **Do not use this device for applications where failure could result in death or serious injury.**



N-CHANNEL MOSFET

DFN5060



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	0.039	0.047	0.80	1.20	
B	0.010		0.254		TYP.
C	0.203	0.219	5.15	5.55	
D	0.234	0.250	5.95	6.35	
E	0.154	0.170	3.92	4.32	
F	0.139	0.154	3.52	3.92	
G	0.197	0.213	5.00	5.40	
H	0.223	0.239	5.66	6.06	
K	0.0444	0.052	1.12	1.32	
J	0.016	0.020	0.41	0.51	
L	0.046	0.054	1.17	1.37	
M	0.022	0.030	0.56	0.76	
N	0.016	0.024	0.40	0.60	

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.3	1.9	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=30A$		6	7.5	m Ω
		$V_{GS}=4.5V, I_D=20A$		7.6	9.5	
Gate Resistance	R_G	f=1MHz, Open drain		1.5		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				75	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=30A$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F=30A, di/dt=100A/\mu s$		55		ns
Reverse Recovery Charge	Q_{rr}			87		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		2460		pF
Output Capacitance	C_{oss}			920		
Reverse Transfer Capacitance	C_{rss}			16		
Total Gate Charge	Q_g	$V_{DS}=50V, V_{GS}=10V, I_D=30A$		39		nC
Gate-Source Charge	Q_{gs}			8		
Gate-Drain Charge	Q_{gd}			7		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, R_G=2.2\Omega, I_D=30A$		15		ns
Turn-On Rise Time	t_r			62		
Turn-Off Delay Time	$t_{d(off)}$			27		
Turn-Off Fall Time	t_f			5		

Curve Characteristics

Fig.1 - Typical Output Characteristics

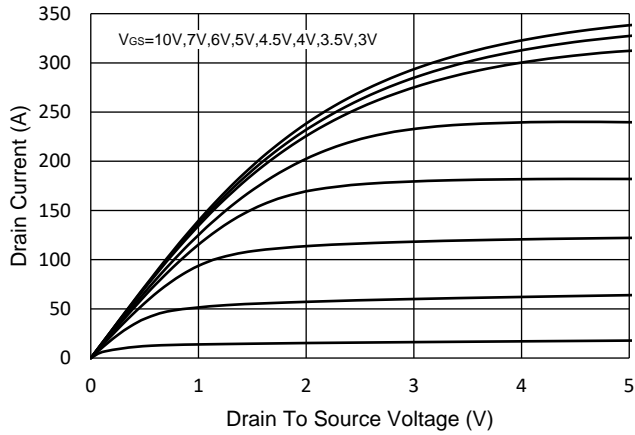


Fig.2 - Transfer Characteristic

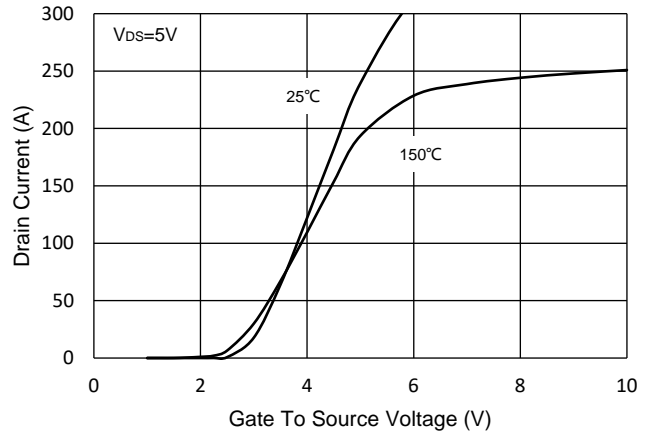


Fig.3 - $R_{DS(ON)} - V_{GS}$

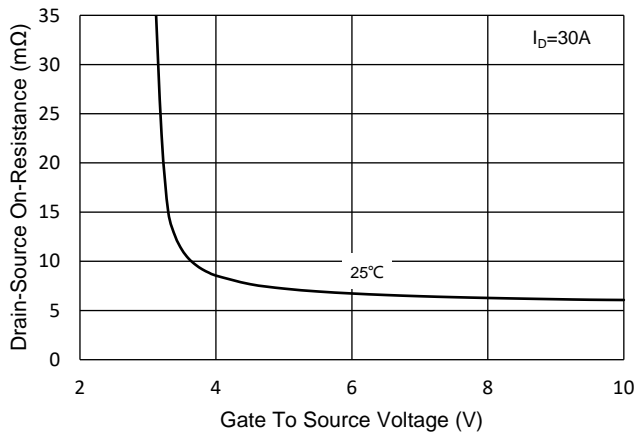


Fig.4 - $R_{DS(ON)} - I_D$

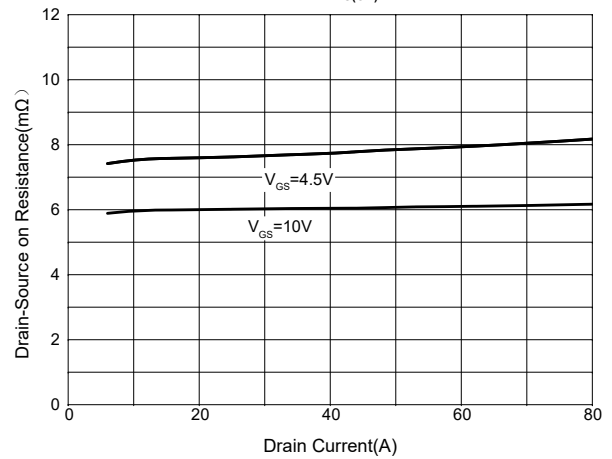


Fig.5 - Capacitance Characteristics

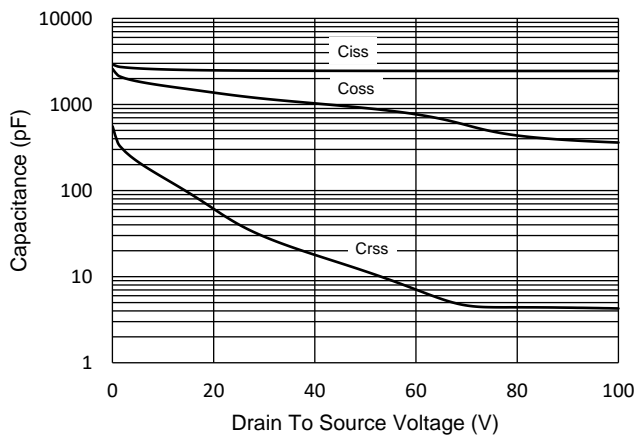
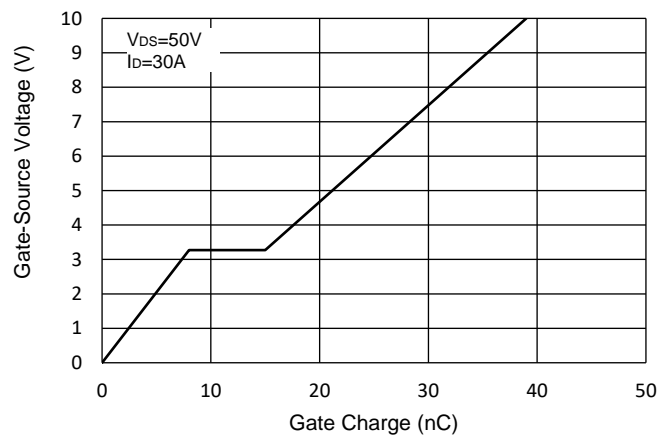


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

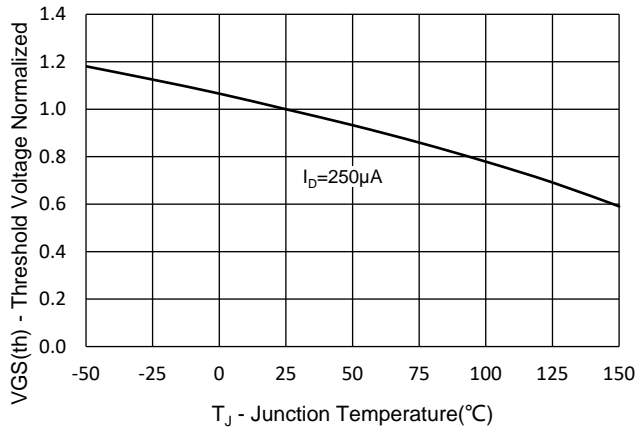


Fig.8 - Normalized On Resistance Characteristics

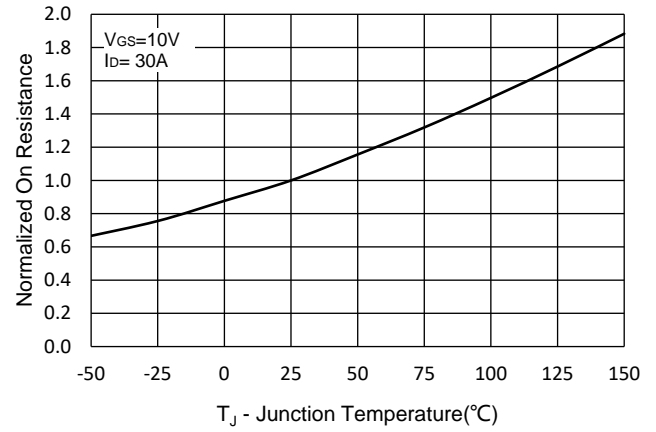


Fig.9 - I_S - V_{SD}

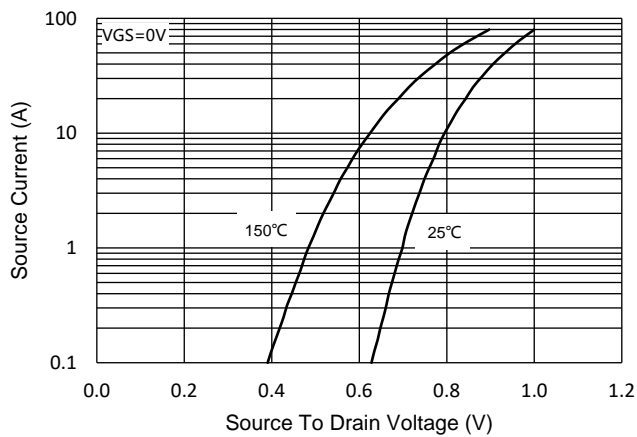


Fig.10 - Drain Current

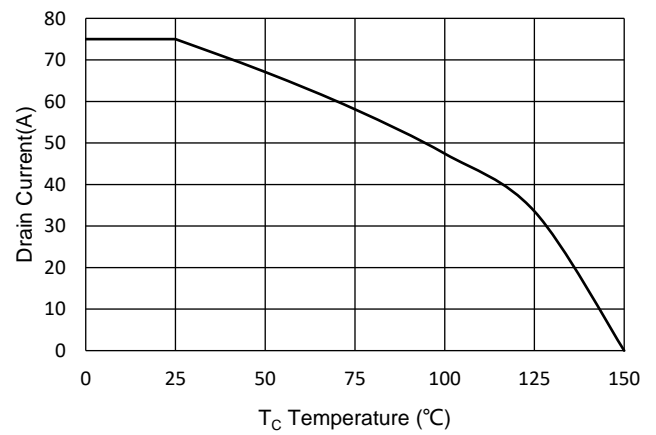
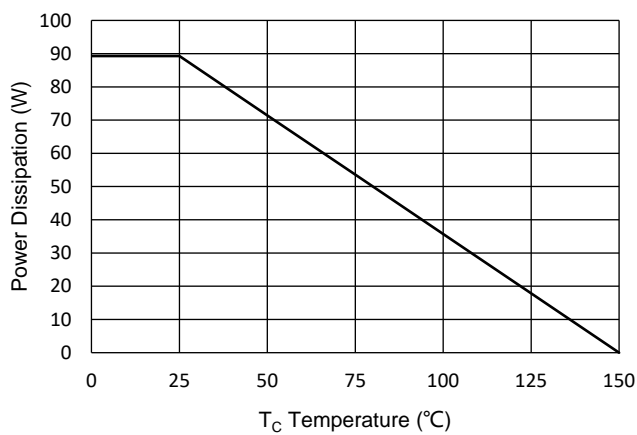


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

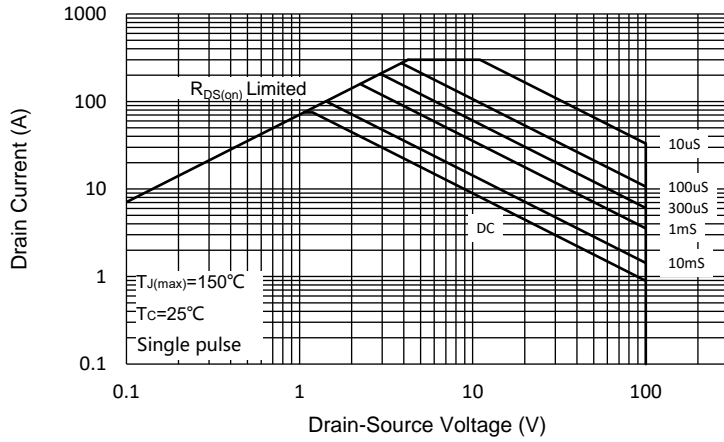
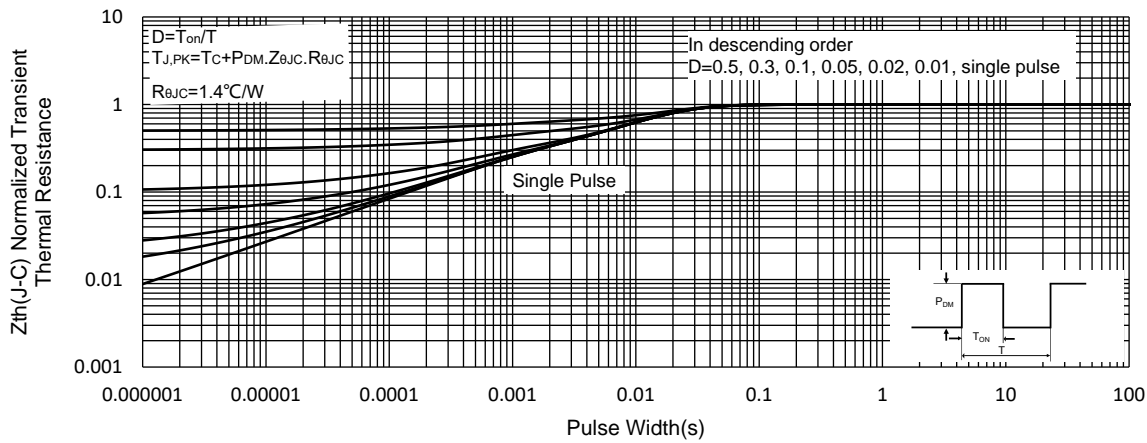


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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